

Product Texts

Zytel® HTN high performance polyamide resins feature high retention of properties upon exposure to elevated temperature, to high moisture, and to harsh chemical environments. Polymer families and grades of Zytel® HTN are tailored to optimize performance as well as processability.

Typical applications with Zytel® HTN include demanding applications in the automotive, electrical and electronics, domestic appliances, and construction industries.

Zytel® HTN55G55TLW BK773 is a 55% glass reinforced high performance polyamide resin with improved toughness and low warpage, developed for structural applications where good flow is needed in thin sections. It is also a PPA resin.

Processing/Physical Characteristics	dry / cond	Unit	Test Standard
ISO Data			
^[C] Molding shrinkage, parallel	0.1 / *	%	ISO 294-4, 2577
^[C] Molding shrinkage, normal	0.2 / *	%	ISO 294-4, 2577

[C]: CAMPUS

Mechanical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Tensile Modulus	21000 / 19000	MPa	ISO 527
^[C] Stress at break	260 / 240	MPa	ISO 527
^[C] Strain at break	1.8 / 1.8	%	ISO 527
^[C] Charpy impact strength, +23°C	80 / -	kJ/m ²	ISO 179/1eU
^[C] Charpy impact strength, -30°C	60 / -	kJ/m ²	ISO 179/1eU
^[C] Charpy notched impact strength, +23°C	21 / -	kJ/m ²	ISO 179/1eA
^[C] Charpy notched impact strength, -30°C	25 / -	kJ/m ²	ISO 179/1eA

[C]: CAMPUS

Thermal properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Temp. of deflection under load, 1.80 MPa	244 / *	°C	ISO 75-1/-2
^[C] Coeff. of linear therm. expansion, parallel	13 / *	E-6/K	ISO 11359-1/-2
^[C] Coeff. of linear therm. expansion, normal	51 / *	E-6/K	ISO 11359-1/-2
^[C] Burning Behav. at thickness h	HB / *	class	IEC 60695-11-10
Thickness tested	0.8 / *	mm	-
Yellow Card available	yes / *	-	-

[C]: CAMPUS

Other properties	dry / cond	Unit	Test Standard
^[C] Humidity absorption	1.2 / *	%	Sim. to ISO 62
^[C] Density	1680 / -	kg/m ³	ISO 1183

[C]: CAMPUS

Characteristics**Processing**

Injection Molding

Delivery form

Pellets

Additives

Release agent

Special Characteristics

High impact or impact modified, Heat stabilized or stable to heat

Features

Low Warpage

Chemical Resistance

General Chemical Resistance

Applications

Automotive, Electrical and Electronical

Regional Availability

North America, South and Central America

Other text information

Injection molding

Lower end of mold temperature range should be used for parts that are ≤ 1 mm.

During molding, use proper protective equipment and adequate ventilation. Avoid exposure to fumes and limit the hold up time and temperature of the resin in the machine. Purge degraded resin carefully with HDPE.